

Features

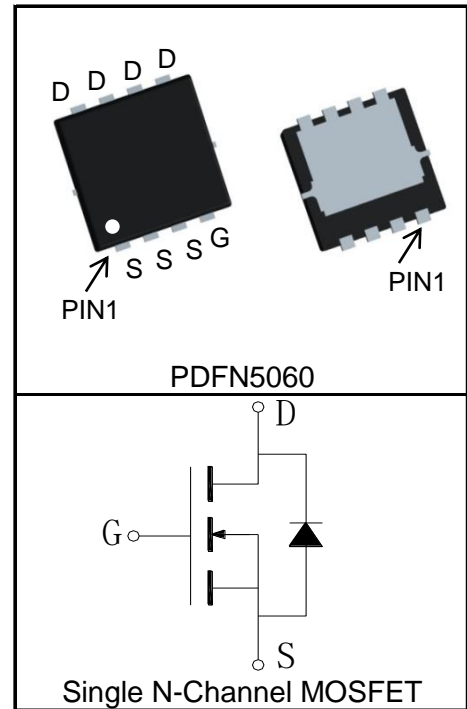
- 20V/60A,
 $R_{DS(ON)} = 3.5m\Omega(Typ.)@V_{GS}=10V$
 $R_{DS(ON)} = 4m\Omega(Typ.)@V_{GS}=4.5V$
 $R_{DS(ON)} = 5m\Omega(Typ.)@V_{GS}=2.5V$
- Low $R_{DS(ON)}$
- Super High Dense Cell Design
- Fast Switching Speed
- 100% avalanche tested

Applications

- Switching Application Systems



Pin Description



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
Common Ratings ($T_C=25^\circ C$ Unless Otherwise Noted)			
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate-Source Voltage	± 12	V
T_J	Maximum Junction Temperature	150	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
I_S	Diode Continuous Forward Current	$T_C=25^\circ C$	60 A
Mounted on Large Heat Sink			
$I_{DP}^{①}$	300 μs Pulse Drain Current Tested	$T_C=25^\circ C$	240 A
$I_D^{②}$	Continuous Drain Current@ $T_C(V_{GS}=4.5V)$	$T_C=25^\circ C$	60
		$T_C=100^\circ C$	38
	Continuous Drain Current@ $T_A(V_{GS}=4.5V)^{③}$	$T_A=25^\circ C$	20
		$T_A=70^\circ C$	16
P_D	Maximum Power Dissipation@ T_C	$T_C=25^\circ C$	32
		$T_C=100^\circ C$	13
	Maximum Power Dissipation@ $T_A^{③}$	$T_A=25^\circ C$	4.2
		$T_A=70^\circ C$	2.7

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.8	°C/W
$R_{\theta JA}$ ^③	Thermal Resistance-Junction to Ambient	30	°C/W
Drain-Source Avalanche Ratings			
E_{AS} ^④	Avalanche Energy, Single Pulsed	64	mJ

Electrical Characteristics ($T_C=25^\circ\text{C}$ Unless Otherwise Noted)

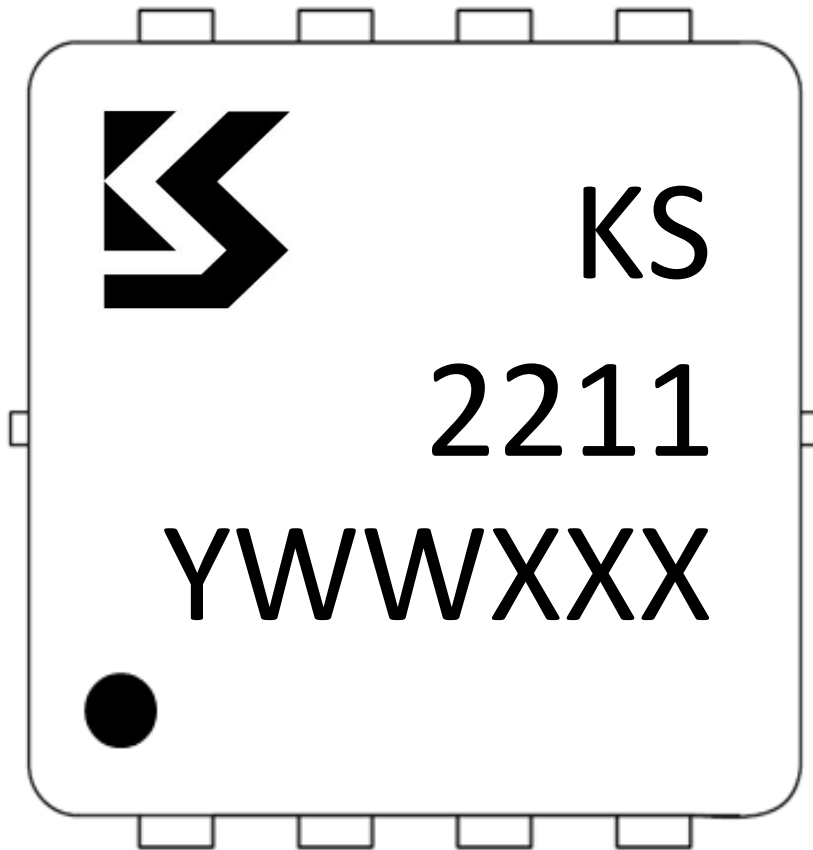
Symbol	Parameter	Test Condition	KS2211NB			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V$			1	μA
		$T_J=125^\circ\text{C}$			30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	0.4	0.7	1	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$			± 100	nA
$R_{DS(ON)}$ ^⑤	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=15A$		3.5	4.5	$m\Omega$
		$V_{GS}=4.5V, I_{DS}=10A$		4	6	$m\Omega$
		$V_{GS}=2.5V, I_{DS}=4A$		5	8	$m\Omega$
Diode Characteristics						
V_{SD} ^⑤	Diode Forward Voltage	$I_{SD}=20A, V_{GS}=0V$		0.83	1.2	V
t_{rr}	Reverse Recovery Time	$I_{SD}=20A, di_{SD}/dt=100A/\mu s$		21		ns
Q_{rr}	Reverse Recovery Charge			39		nC
Dynamic Characteristics ^⑥						
R_G	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$		2.8		Ω
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=10V, \text{Frequency}=1.0\text{MHz}$		2500		μF
C_{oss}	Output Capacitance			410		
C_{riss}	Reverse Transfer Capacitance			365		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=10V, I_{DS}=20A, V_{GEN}=4.5V, R_G=3\Omega$		16		ns
t_r	Turn-on Rise Time			9		
$t_{d(OFF)}$	Turn-off Delay Time			35		
t_f	Turn-off Fall Time			17		
Gate Charge Characteristics ^⑥						
Q_g	Total Gate Charge	$V_{DS}=10V, V_{GS}=4.5V, I_{DS}=20A$		27		nC
Q_{gs}	Gate-Source Charge			9		
Q_{gd}	Gate-Drain Charge			11		

Notes:

- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature.
- ③When mounted on 1 inch square copper board, $t \leq 10\text{sec}$.
- ④Limited by $T_{J\text{max}}$, $I_{AS} = 36\text{A}$, $L = 0.1\text{mH}$, $V_{DD} = 10\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.
- ⑤Pulse test; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- ⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS2211NB	PDFN5060	Tape&Reel	5000	13"	12mm

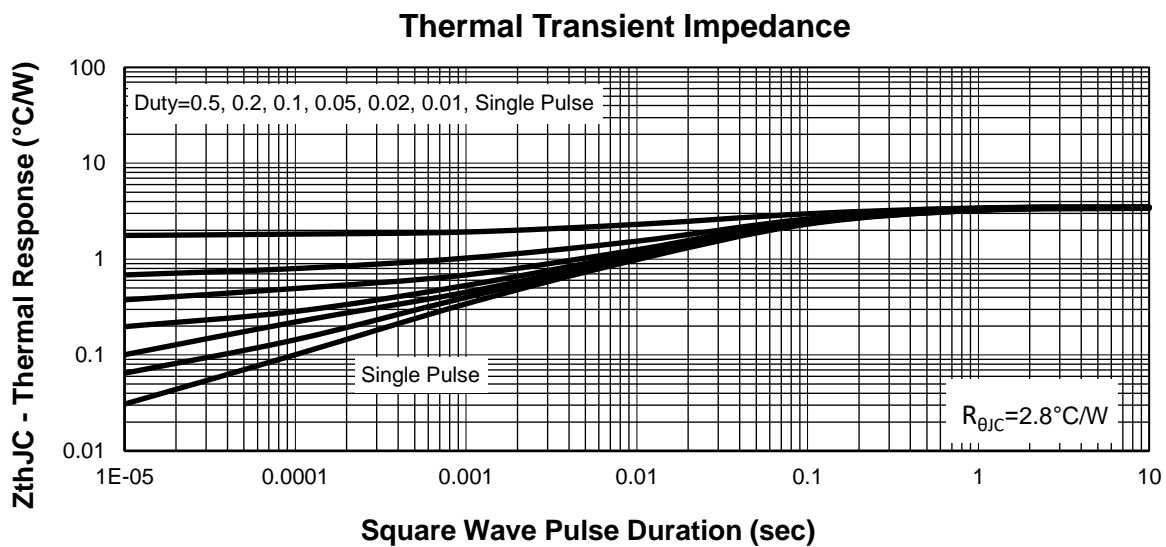
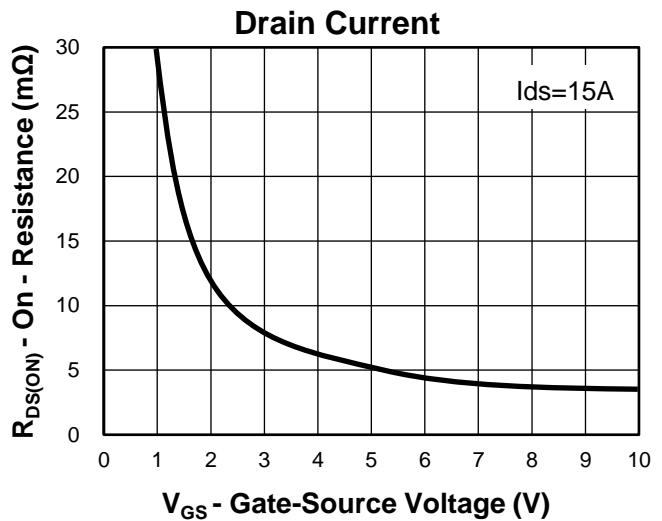
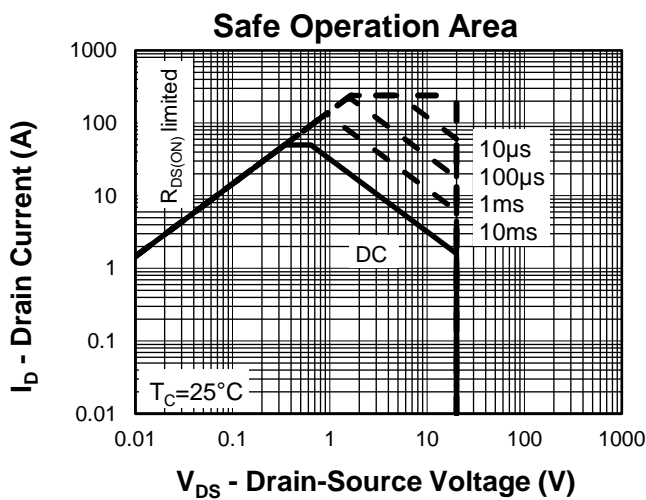
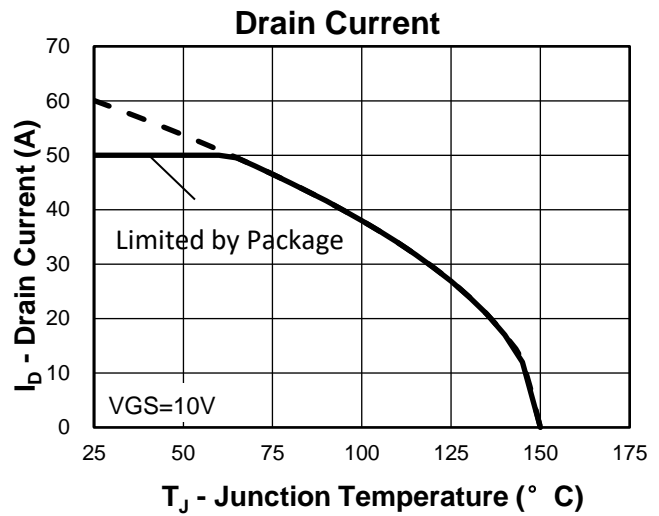
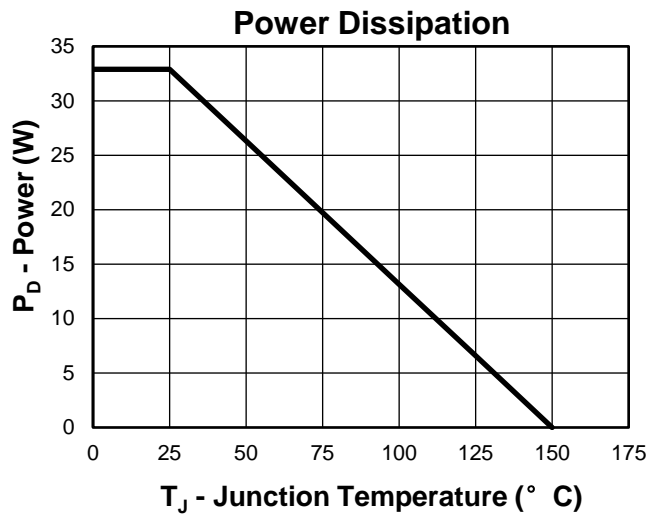


Y =Year,2017-A,2018-B,etc.

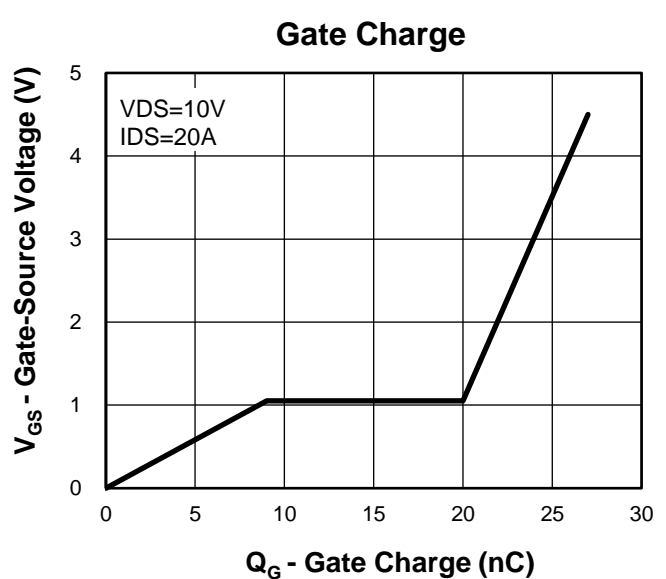
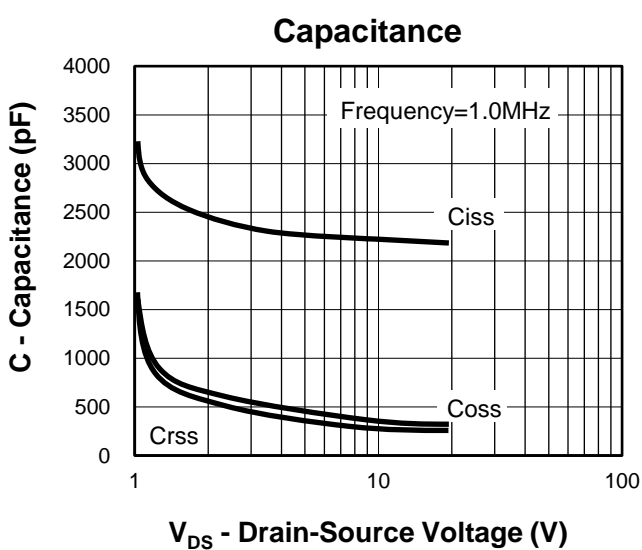
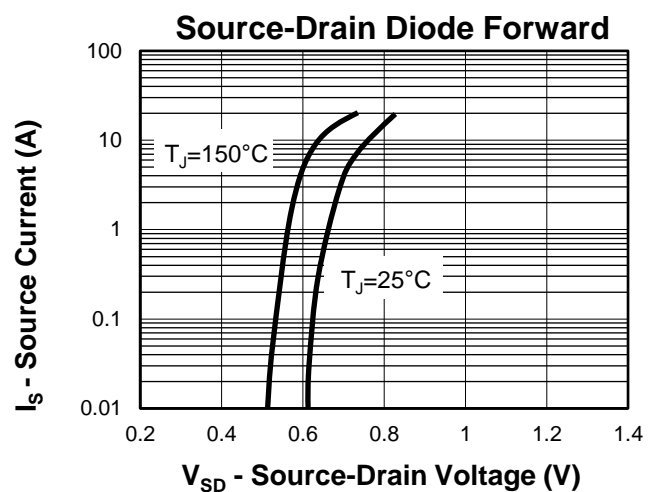
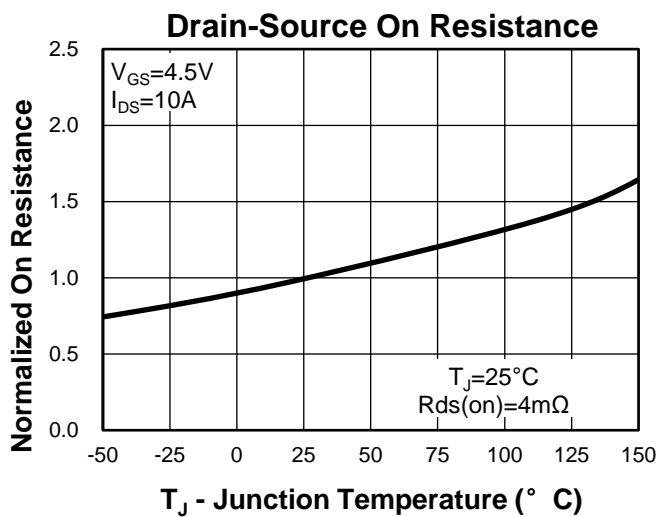
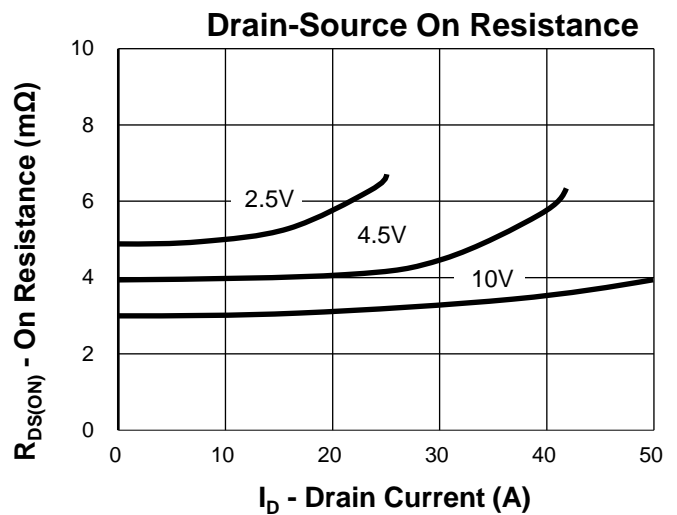
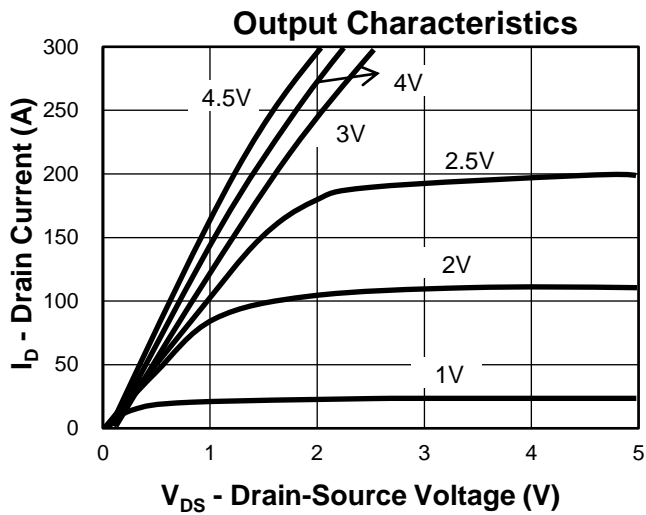
WW =Week.

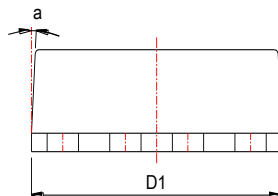
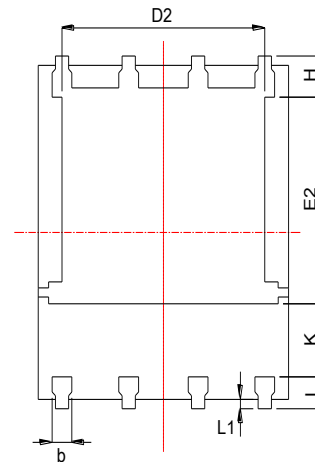
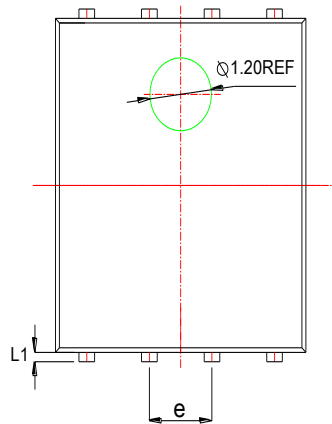
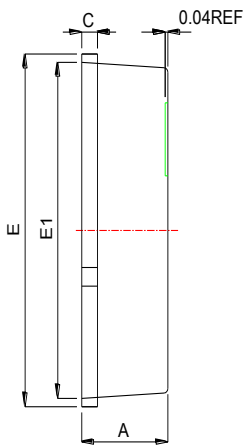
XXX =Lot number.

Typical Characteristics

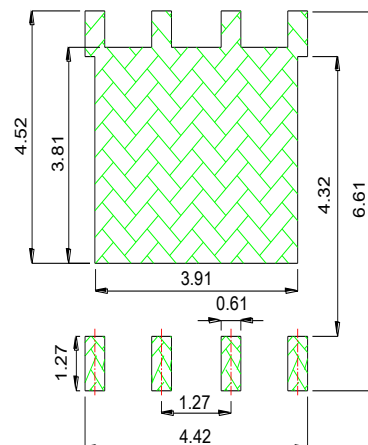


Typical Characteristics



Package Information
PDFN5060


Land Pattern
(Only for Reference)



SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.90	1.00	1.10	0.035	0.039	0.043
b	0.33	0.42	0.51	0.013	0.017	0.020
c	0.20	0.25	0.30	0.008	0.010	0.012
D1	4.80	4.90	5.00	0.189	0.193	0.197
D2	3.61	3.79	3.96	0.142	0.149	0.156
E	5.90	6.00	6.10	0.232	0.236	0.240
E1	5.65	5.75	5.85	0.222	0.226	0.230
E2	3.38	3.58	3.78	0.133	0.141	0.149
e	1.27 BSC			0.050 BSC		
H	0.41	0.51	0.61	0.016	0.020	0.024
k	1.10			0.043		
L	0.51	0.61	0.71	0.020	0.024	0.028
L1	0.06	0.13	0.20	0.002	0.005	0.008
a	0°		12°	0°		12°

Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

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